Xbox One Heat Sink Assembly Replacement

This guide will allow you to replace the inner metal shell and the enclosed heat sink. It is a prerequisite to replacing the motherboard, the colour camera, the infra-red camera, and the infra-red blasters (the projector).

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INTRODUCTION

The heat sink assembly is found within the Kinect. A number of components are mounted on it, including the colour camera, IR camera, and IR blasters.

TOOLS:

- T9 Torx Screwdriver (1)
- Spudger (1)
- Tweezers (1)
### Step 1 — Outer Shell

- Remove the sticker on the underside of the device.
- Remove the four 3.1x7.7 mm T9 screws underneath the sticker.
- While you’re at it, remove the four 3.1x23.6 mm T9 screws beneath the sticker. Make note of the sizes and locations of the screws.

### Step 2

- Remove the back panel.
- Remove the black panels on either side of the Kinect, and remove the 3.1x7.7 mm T9 screws underneath them.
Step 3

- Using your thumbs, press firmly against the outer case on either side of the stand. This will disengage the internal assembly.

- Lift the internal assembly with the spudger.

- Remove the assembly from the case. You now have access to the inner shell of the Kinect, along with the heat sink, microphone, and LED sensor.

Step 4 — Heat Sink Assembly

- Remove the eight 2.9x7.6 mm T9 screws from the rear of the internal case.

- Lift the internal metal case from the plastic shell enclosing the heat sink assembly.
Step 5

- Disconnect the ribbon cable between the sensor driver board and the motherboard.
- Remove the 3.0x7.5 mm T9 screw holding the sensor driver board to the heat sink.
- Remove the infrared sensor board for the Kinect.

Step 6

- Detach the ribbon cable leading to the microphone with the tweezers.
- Remove the four 3.1x7.7 mm T9 screws connecting the microphone to the heat sink assembly.
- Remove the stand.
Step 7

- Remove the eight 3.0x7.6 mm T9 screws from the motherboard.
- Peel away the plastic film from the motherboard using the spudger.
- Detach the ribbon cable leading to the color camera using the spudger.

Step 8

- Lift the motherboard and the heat sink assembly from the plastic shell. The components attached to the heat sink are now accessible.

To reassemble your device, follow these instructions in reverse order.